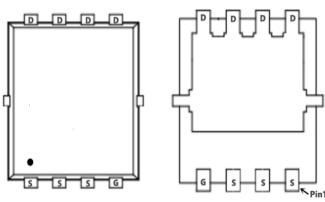
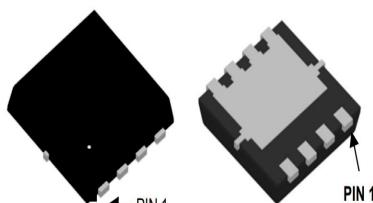
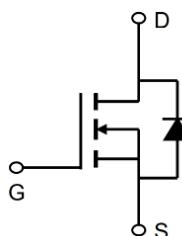


## TM30N06NF

## N-Channel Enhancement Mosfet

<b>General Description</b> <ul style="list-style-type: none"> <li>Low <math>R_{DS(ON)}</math></li> <li>RoHS and Halogen-Free Compliant</li> </ul> <b>Applications</b> <ul style="list-style-type: none"> <li>Load switch</li> <li>PWM</li> </ul>	<b>General Features</b> <p><math>V_{DS} = 60V</math> <math>I_D = 30A</math></p> <p><math>R_{DS(ON)} = 24 m\Omega</math>(typ.) @ <math>V_{GS} = 10V</math></p> <p>100% UIS Tested 100% <math>R_g</math> Tested</p> 
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   <b>Marking: 30N06</b>		<b>NF:DFN5x6-8L</b>
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<b>Absolute Maximum Ratings</b> ( $T_c=25^\circ C$ unless otherwise specified)			
<b>Symbol</b>	<b>Parameter</b>	<b>Rating</b>	<b>Units</b>
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	30	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	19	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	111	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	50	mJ
$I_{AS}$	Avalanche Current	30	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation <sup>4</sup>	20	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

<b>Thermal Data</b>				
<b>Symbol</b>	<b>Parameter</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	60	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.063	---	$\text{V}/^\circ\text{C}$
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10\text{V}$ , $I_D=15\text{A}$	---	24	33	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=10\text{A}$	---	32	38	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	1.2	1.7	2.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-5.24	---	$\text{mV}/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{DS}=48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=5\text{V}$ , $I_D=15\text{A}$	---	17	---	S
$R_g$	Gate Resistance	$V_{DS}=0\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	3.2	---	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{DS}=48\text{V}$ , $V_{GS}=4.5\text{V}$ , $I_D=12\text{A}$	---	12.6	---	$\text{nC}$
$Q_{gs}$	Gate-Source Charge		---	3.2	---	
$Q_{gd}$	Gate-Drain Charge		---	6.3	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=30\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=3.3\Omega$ , $I_D=10\text{A}$	---	8	---	$\text{ns}$
$T_r$	Rise Time		---	14.2	---	
$T_{d(off)}$	Turn-Off Delay Time		---	24.4	---	
$T_f$	Fall Time		---	4.6	---	
$C_{iss}$	Input Capacitance	$V_{DS}=15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	1378	---	$\text{pF}$
$C_{oss}$	Output Capacitance		---	86	---	
$C_{rss}$	Reverse Transfer Capacitance		---	64	---	

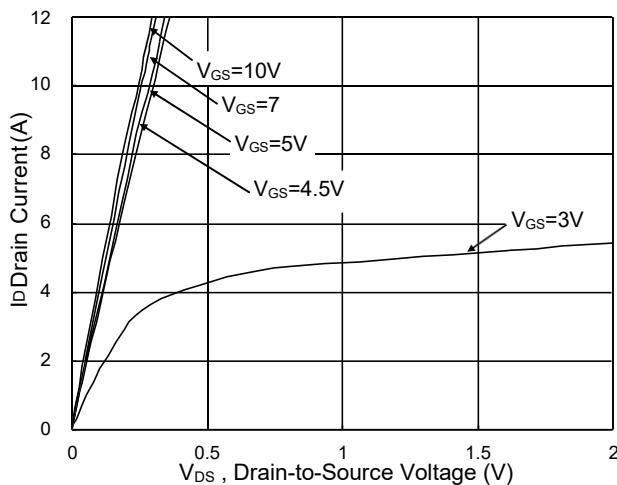
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	30	A
$I_{SM}$	Pulsed Source Current <sup>2,5</sup>		---	---	111	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.2	V

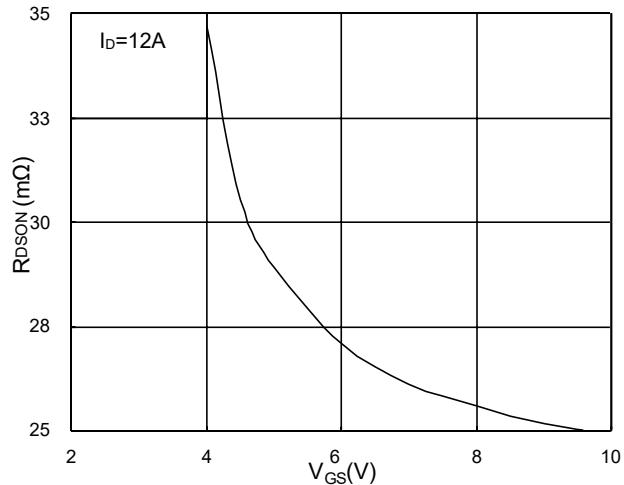
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25\text{V}$ , $V_{GS}=10\text{V}$ , $L=0.1\text{mH}$ , $I_{AS}=22.6\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

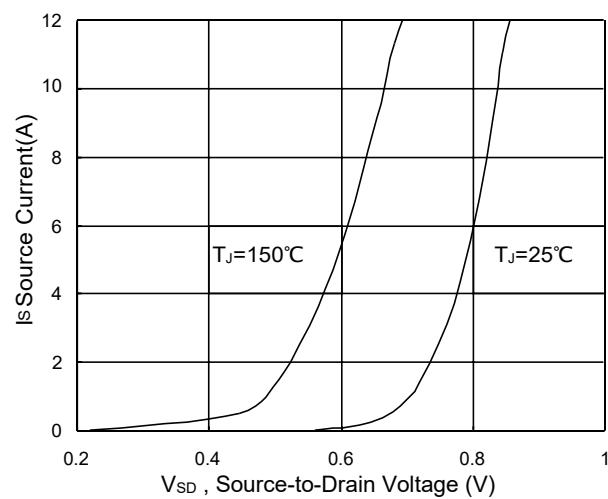
### Typical Characteristics



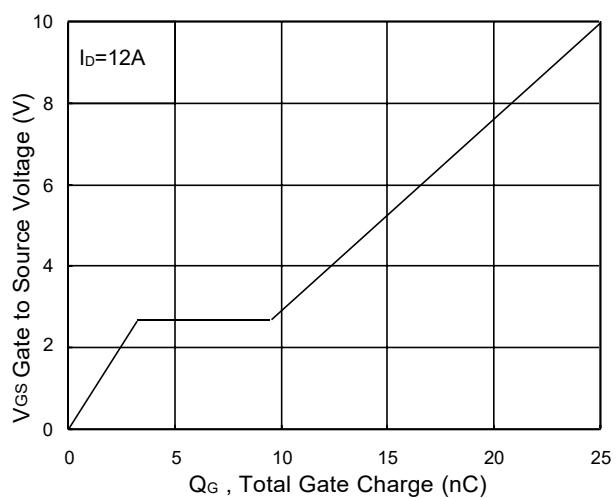
**Fig.1 Typical Output Characteristics**



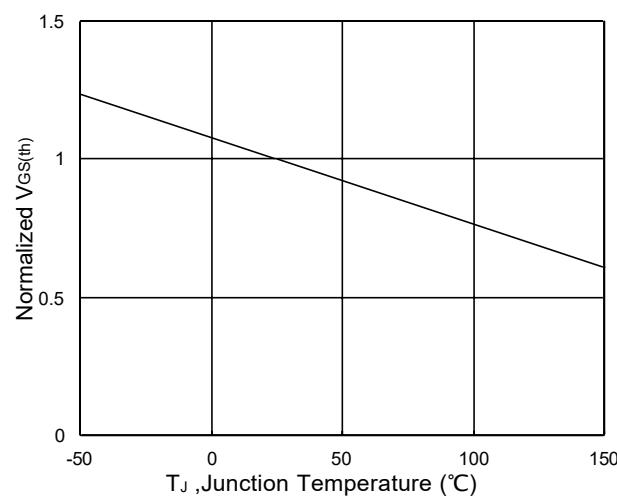
**Fig.2 On-Resistance v.s Gate-Source**



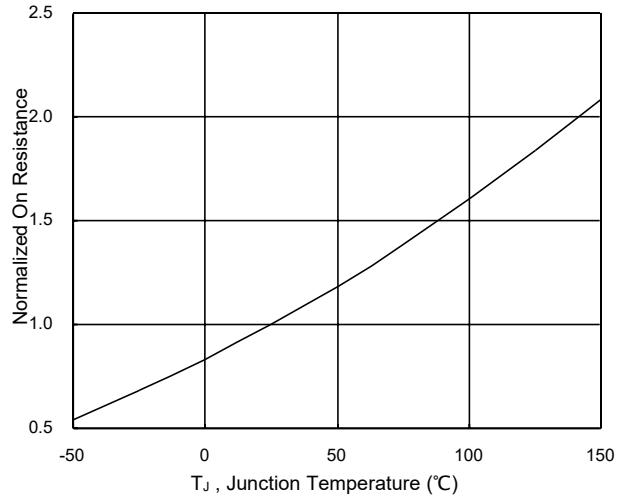
**Fig.3 Forward Characteristics of Reverse**



**Fig.4 Gate-Charge Characteristics**



**Fig.5 Normalized V<sub>Gs(th)</sub> v.s T<sub>j</sub>**



**Fig.6 Normalized R<sub>DSON</sub> v.s T<sub>j</sub>**

## TM30N06NF

## N-Channel Enhancement Mosfet

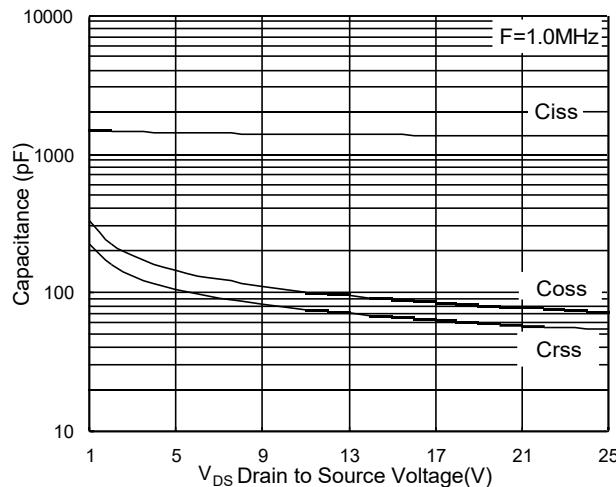


Fig.7 Capacitance

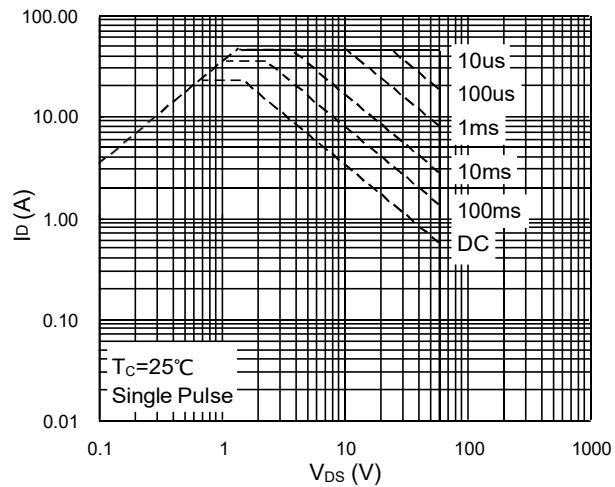


Fig.8 Safe Operating Area

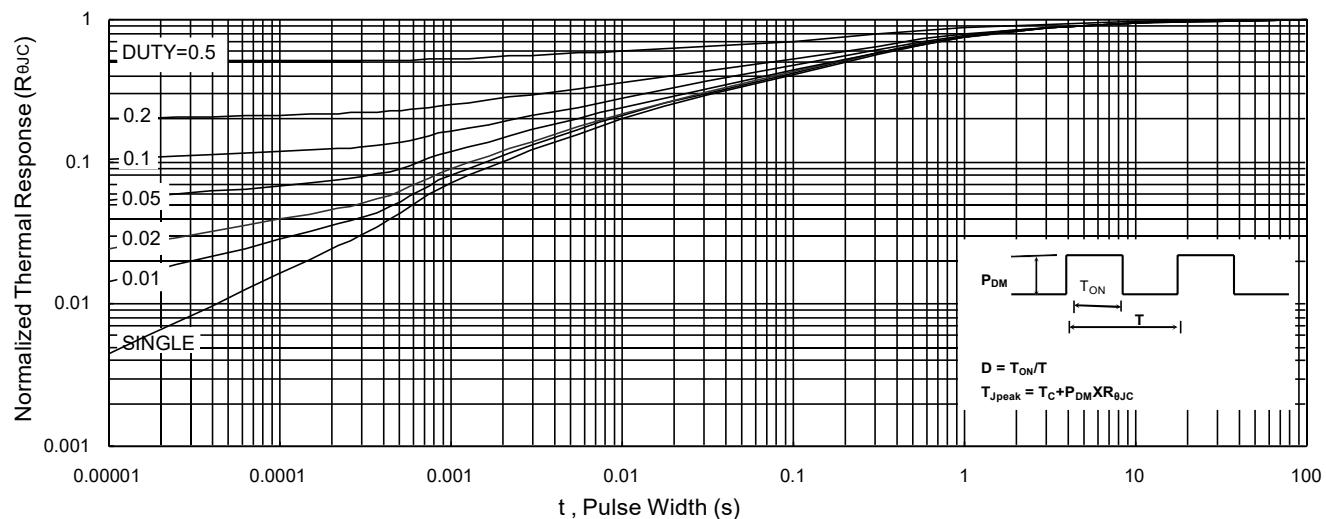


Fig.9 Normalized Maximum Transient Thermal Impedance

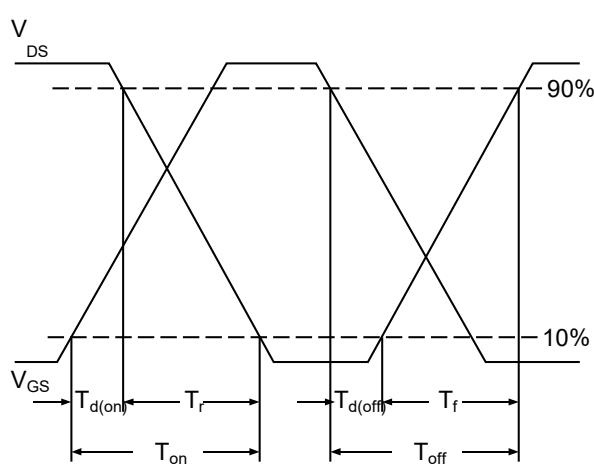


Fig.10 Switching Time Waveform

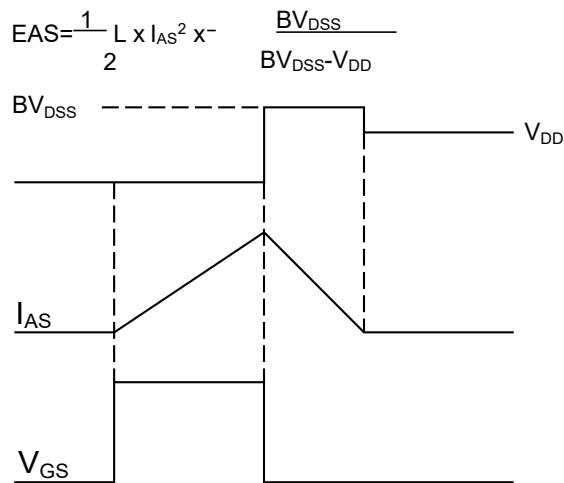
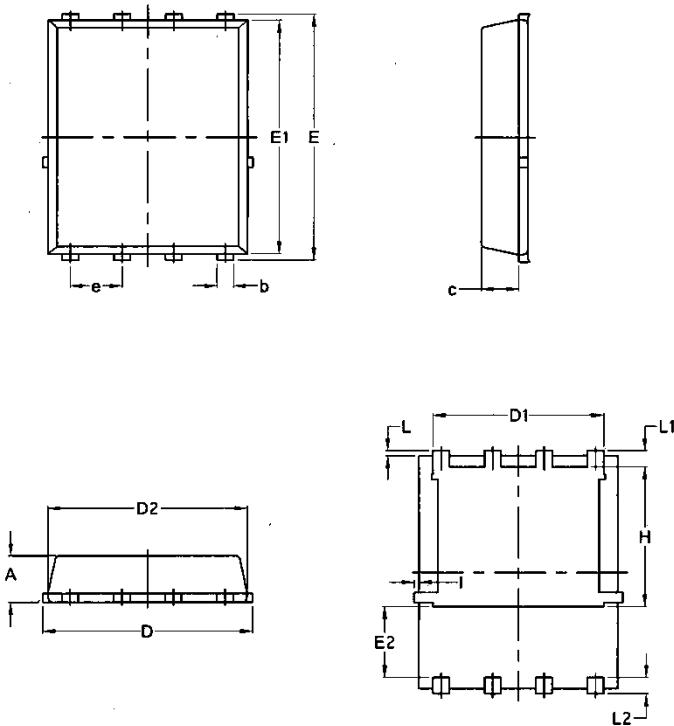


Fig.11 Unclamped Inductive Waveform

## Package Mechanical Data:DFN5x6-8L



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070